

SEMICONDUCTOR

# **MMSZ4689**

### **General Description**

### **Features**

· Compact surface mount with same footprint as mini-melf

Half watt, General purpose, Medium Current Surface Mount Zener in the SOD-123 package. The SOD-123 package has the same footprint as the glass mini-melf (LL-34) package & provides a convenient alternative to the Leadless package.

## • 500mW rating on FR-4 or FR-5 board.

• Class 3 ESD rating (>16kV) per Human Body Model

### Ordering

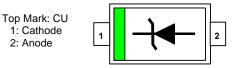
• 7 inch reel (178mm); 8mm Tape; 3,000 units per reel.

| Symbol                                           | Parameter                                            | Value      | Units       |
|--------------------------------------------------|------------------------------------------------------|------------|-------------|
| STG                                              | Storage Temperature                                  | -55 ~ 150  | °C          |
| J                                                | Maximum Junction Temperature                         | -55 ~ 150  | °C          |
| D                                                | Total Power Dissipation at 25°C<br>Derate above 25°C | 500<br>6.7 | mW<br>mW/°C |
| R <sub>QJA</sub>                                 | Thermal Resistance Junction to Ambient               | 340        | °C/W        |
| QJA<br>QJL                                       | Thermal Resistance Junction to Lead                  | 150        | °C/W        |
| Vz                                               | Maximum Voltage Change (note 2)                      | 970        | mV          |
| Lead Solder Temperature (Max 10 second duration) |                                                      | 260        | °C          |
| Nominal Zener Voltage (V <sub>7</sub> ) at 50μA  |                                                      | 5.1        | V           |

Absolute Maximum Ratings (note 1) T<sub>A</sub>=25°C unless otherwise noted

Note 1: These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

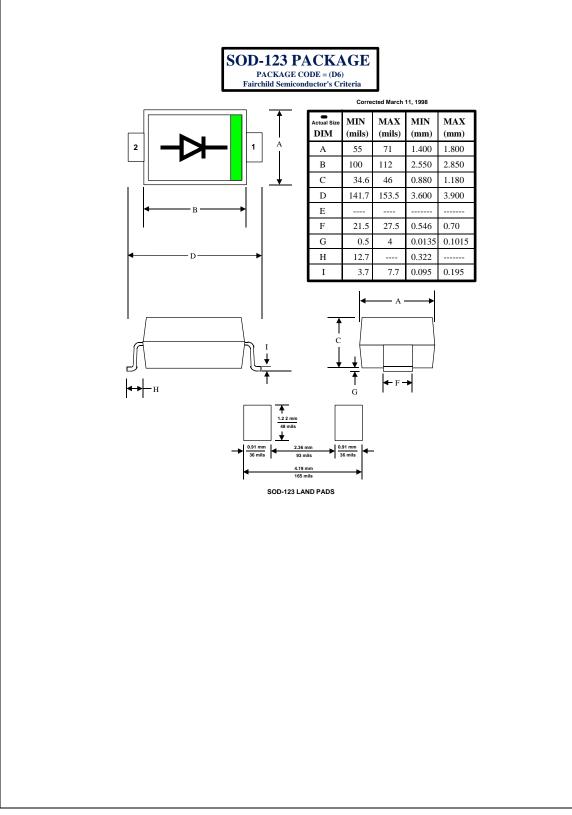
Note 2: Voltage change is equal to the difference between  $V_{Z}$  at 100µA and  $V_{Z}$  at 10µA.



## Electrical Characteristics TA=25°C unless otherwise noted

| Symbol         | Characteristics              | Test Conditions                  | Min. | Max. | Units |
|----------------|------------------------------|----------------------------------|------|------|-------|
| VZ             | Zener Voltage                | $I_{ZT} = 50\mu A_{D.C}$         | 4.85 | 5.36 | V     |
| I <sub>R</sub> | Reverse Leakage              | V <sub>R</sub> = 3.0V            |      | 10   | μA    |
| V <sub>F</sub> | Forward Voltage              | I <sub>F</sub> = 10mA            |      | 900  | mV    |
| $\Delta V_Z$   | Delta Zener Voltage (Note 2) | $I_{ZT} = 100\mu A$ to $10\mu A$ |      | 970  | mV    |

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| Bottomless™ FAS1                      | T®               | LittleFET™             | Power247™                    | SuperSOT™-3           |
| CoolFET™ FAS1                         | Tr™              | MicroFET™              | PowerTrench <sup>®</sup>     | SuperSOT™-6           |
| CROSSVOLT™ FRFE                       | ET™              | MicroPak™              | QFET <sup>®</sup>            | SuperSOT™-8           |
| DOME™ Globa                           | oalOptoisolator™ | MICROWIRE™             | QS™                          | SyncFET™              |
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**Definition of Terms** 

| Datasheet Identification | Product Status            | Definition                                                                                                                                                                                                                        |
|--------------------------|---------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
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